

2SJ483 Silicon P Channel MOS FET

REJ03G0867-0200 (Previous: ADE-208-519) Rev.2.00 Sep 07, 2005

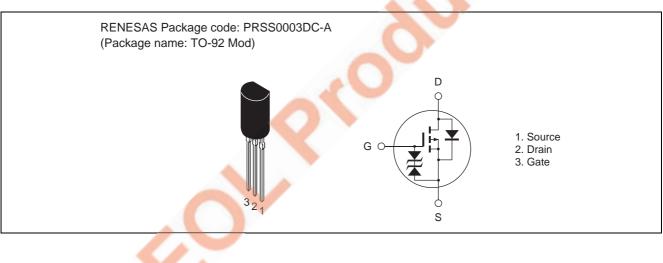
Description

High speed power switching

Features

- Low on-resistance $R_{DS\;(on)}=0.08\;\Omega\;typ\;(at\;V_{GS}=-10\;V,\,I_D=-2.5\;A)$
- 4 V gate drive devices.
- Large current capacitance $I_D = -5 A$

Outline





Absolute Maximum Ratings

		(Ta = 25°C)
Symbol	Value	Unit
V _{DSS}	-30	V
V _{GSS}	±20	V
ID	-5	А
I _{D (pulse)} Note 1	-20	А
I _{DR}	-5	А
Pch	0.9	W
Tch	150	۵°
Tstg	-55 to +150	°C
	V _{DSS} V _{GSS} I _D I _{D (pulse)} ^{Note 1} I _{DR} Pch Tch	VDSS -30 VGSS ±20 ID -5 ID(pulse) -20 IDR -5 Pch 0.9 Tch 150

Note: 1. PW \leq 10 μ s, duty cycle \leq 1%

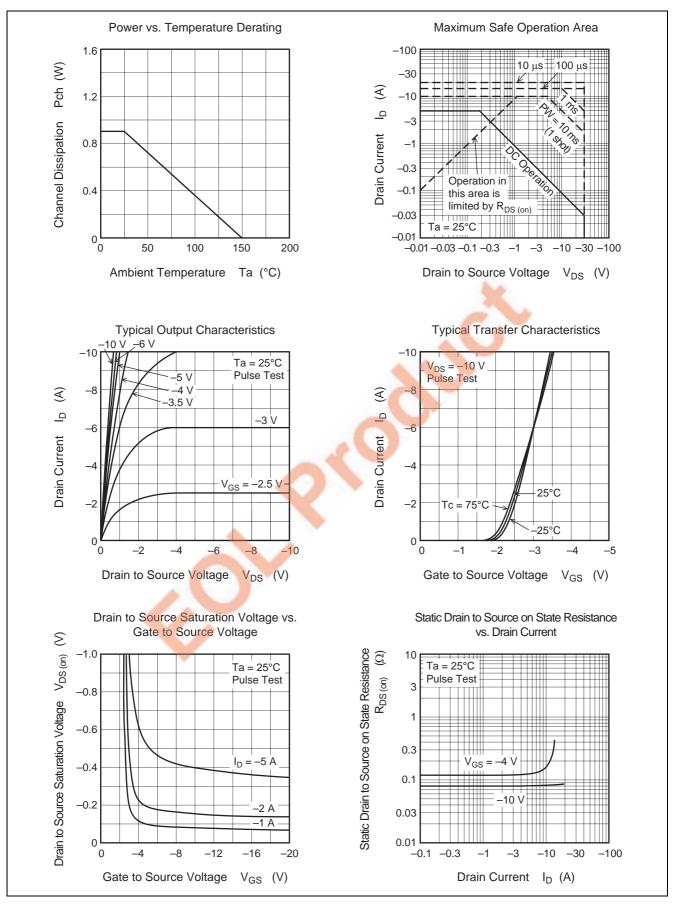
Electrical Characteristics

						$(Ta = 25^{\circ}C)$
Item	Symbol	Min	Тур	Max	Unit	Test Conditions
Drain to source breakdown voltage	V (BR) DSS	-30		—	V	$I_{D} = -10 \text{ mA}, V_{GS} = 0$
Gate to source breakdown voltage	V (BR) GSS	±20		—	V	$I_{G} = \pm 100 \ \mu A, \ V_{DS} = 0$
Zero gate voltage drain current	I _{DSS}	—	_	-10	μA	$V_{DS} = -30 \text{ V}, \text{ V}_{GS} = 0$
Gate to source leak current	I _{GSS}	—	—	±10	μA	$V_{GS} = \pm 16 \text{ V}, V_{DS} = 0$
Gate to source cutoff voltage	V _{GS (off)}	-1.0	-	-2.0	V	$I_D = -1 \text{ mA}, V_{DS} = -10 \text{ V}$
Static drain to source on state resistance	R _{DS (on)}	_	0.08	0.11	Ω	$I_D = -2.5 \text{ A}, V_{GS} = -10 \text{ V}^{\text{Note 2}}$
	R _{DS (on)}	—	0.12	0.17	Ω	$I_D = -2.5 \text{ A}, V_{GS} = -4 \text{ V}^{\text{Note 2}}$
Forward transfer admittance	y _{fs}	3	5		S	$I_D = -2.5 \text{ A}, V_{DS} = -10 \text{ V}^{\text{Note 2}}$
Input capacitance	Ciss		630	_	pF	$V_{DS} = -10 \text{ V}$
Output capacitance	Coss		390	—	pF	$V_{GS} = 0$
Reverse transfer capacitance	Crss		135	_	pF	f = 1 MHz
Turn-on delay time	t _{d (on)}	_	15	—	ns	$V_{GS} = -10 \text{ V}$
Rise time	t,	-	70	_	ns	$I_{\rm D} = -2.5 \text{ A}$
Turn-off delay time	t _{d (off)}	—	65	—	ns	$R_L = 4 \Omega$
Fall time	t		60		ns	
Body to drain diode forward voltage	VDF		-1.0	—	V	$I_F = -5 A, V_{GS} = 0$
Body to drain diode reverse recovery time	t _{rr}		60		ns	$I_F = -5 A, V_{GS} = 0$
						$di_F/dt = 20 A/\mu s$

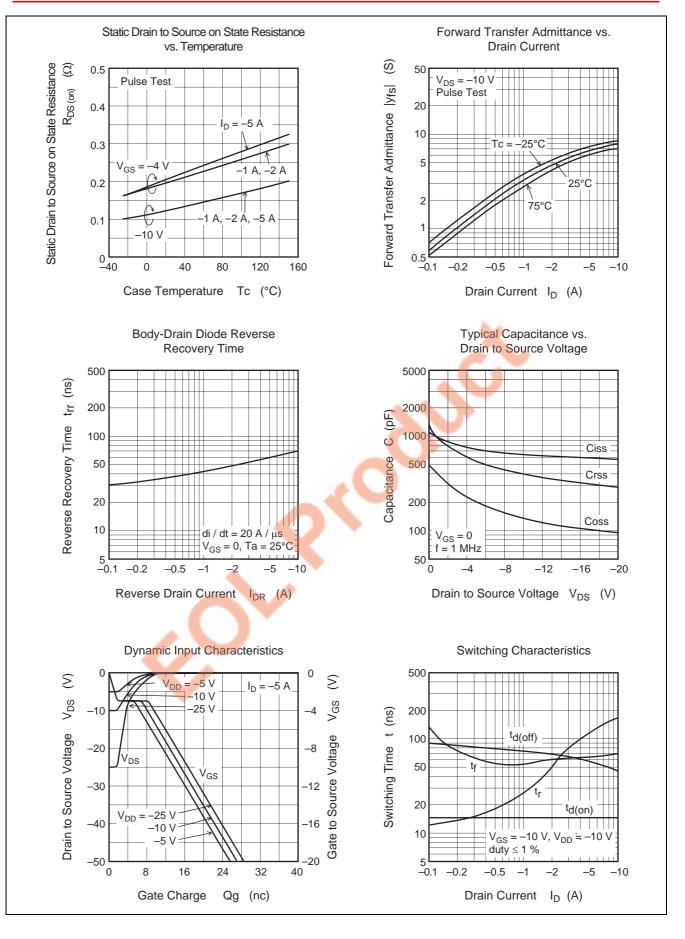
Note: 2. Pulse test



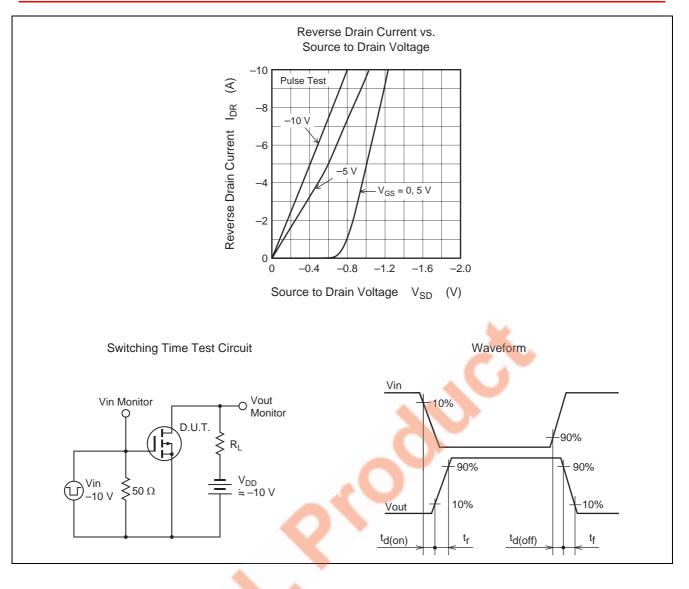
Main Characteristics







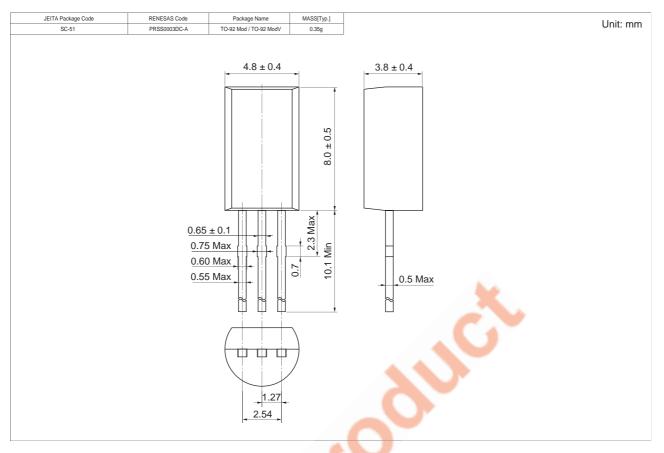
RENESAS







Package Dimensions



Ordering Information

Part Name	Quantity	Shipping Container
2SJ483TZ-E	2500 pcs 🔪	Taping

Note: For some grades, production may be terminated. Please contact the Renesas sales office to check the state of production before ordering the product.



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